

Abstract

To control peel strength at an organic adhesive interface between a carrier foil and a copper-microparticle layer which constitute an electrodeposited copper foil with
5 carrier. In the present invention, (1) a barrier copper layer is formed on the adhesive interface layer and copper microparticles are formed on the barrier layer; (2) the anti-corrosion treatment is carried out by use of a plating bath containing a single metallic component or a plurality of
10 metallic components for forming an alloy, the plating bath(s) having a deposition potential less negative than -900 mV (vs. AgCl/Ag reference electrode); and (3) methods (1) and (2) are combined.